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(54) **SEMICONDUCTOR INTEGRATED CIRCUIT
DEVICE**

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ABSTRACT

A semiconductor integrated circuit device includes: a terminal; an internal resistor that is any one of a pull-up resistor configured so that a first end of the pull-up resistor is connected to the terminal and a first constant voltage is applied to a second end of the pull-up resistor, or a pull-down resistor configured so that a first end of the pull-down resistor is connected to the terminal and a ground voltage is applied to a second end of the pull-down resistor; and an AD converter configured so that a voltage of the terminal is converted into digital data having a number of bits of 2 or more.

